PC SOCIATION CONNECTING CTRONICS INDUSTRIES* Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
			Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and M					lfg Informa	tion				
upplier Information														
Company name* Company uniq			que ID U			Unique ID Authority				Respon	Response Date*			
nsemi										2024-0	2024-05-21			
ontact Name	tact Name Title - Contact					Phone - Contact*				Email ·	Email - Contact*			
Product-Env-Stewards Product Enviro Cor			ro Compliance	o Compliance		NA			Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - Representati			ntative		Phone - Representative*			Email ·	Email - Representative*					
Product-Env-Stewards Product E			uct Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Requester Item Number	Requester Item Number Mfr Item N		Number Mfr Item Name			Effective Date	ctive Date Version Manufacturing Site		lanufacturing Site		Weight*	UOM	Unit Type	
	N01S830	N01S830BAT22I 1MB, 3V, BATT B		BU FUNCT		2024-05-21 Т		TH6		32.92	mg	Each		
Ianufacturing Proccess Informat	tion		•											
Terminal Plating / Grid Array Ma	terial T	ial Terminal Base Alloy		J-STD-020 MSI	L Rating	Peak Proce	rocess Body Temperature Max Time at Peak		k Tempera	ture Num	ber of Reflow Cyc	les		
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		3		260		С	30	seco	nds 3			
omments														
FTENTION: MSL 3 Rated item requires	s Bake and D	ry Pack (after	electrical test)											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless otherwise noted).									
Homogeneous Material Weight		Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	1.65	mg	Supplier	Silicon (Si)	7440-21-3		1.65	mg	
Die Attach	0.9	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.18	mg	
			Supplier	Silver (Ag)	7440-22-4		0.72	mg	
Lead Frame	10.6	mg	Supplier	Magnesium (Mg)	7439-95-4		0.0159	mg	
			Supplier	Silicon (Si)	7440-21-3		0.0689	mg	
			В	Nickel (Ni)	7440-02-0		0.318	mg	
			Supplier	Copper (Cu)	7440-50-8		10.1972	mg	
Mold Compound-Black	19.11	mg		Epoxy Phenol Resin	proprietary data		2.6754	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		16.4346	mg	
Plating	0.44	mg	Supplier	Tin (Sn)	7440-31-5		0.44	mg	
Wire Bond - Au	0.22	mg	Supplier	Gold (Au)	7440-57-5		0.22	mg	